

**Amendments to the Specification:**

**Please replace the paragraph beginning at page 2, line 13, with the following amended paragraph:**

-- In recent years, however, arrangement of high bumps in a high density has been required for many devices. If a usual adhesive sheet "A" for surface protection is used for such devices, the adhesive layer cannot be stuck to the edge of the wafer because of an obstacle of the bump, as shown in Fig. 4. As a result, a part of cleaning water that is sprayed for the purpose of removing heat or grinding dust generated during the back surface grinding process sometimes penetrates to the circuit surface ~~side to thereby~~ side, thereby fouling the circuit surface. --